ASDM30N40TD

30V N-Channel MOSFET

Features

- Low RDS(ON)
- Low Dense Cell Design
- Reliable and Rugged
- Advanced trench process technology

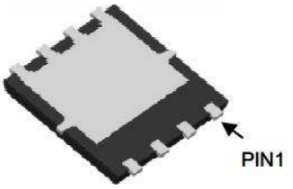
Product Summary

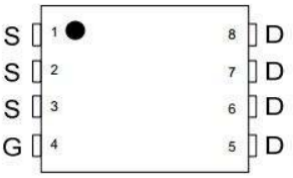
RoHs

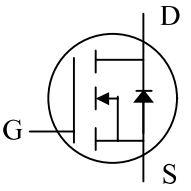
V_{DS}	30	V
$R_{DS(on),TYP}$@ V_{GS}=10 V	7.2	mΩ
I_D	40	A

Application

- Power Management in Inverter System
- Synchronous Rectification







Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_A=25℃	Continuous Drain Current[3]	40	A
I_D@T_A=70℃	Continuous Drain Current[3]	30.5	A
I_{DM}	Pulsed Drain Current[1]	50	A
P_D@T_A=25℃	Total Power Dissipation	2.5	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient[3]	50	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	30	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=12A	-	7.2	9	mΩ
		V_{GS}=4.5V, I_D =8A	-	11	17	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	1.4	2.5	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=12A	-	24	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V, V_{GS}=0V	-	-	10	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=12A	-	15	24	nC
Q_{gs}	Gate-Source Charge	V_{DS}=15V	-	4	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	7	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=15V	-	10	-	ns
t_r	Rise Time	I_D=1A	-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω	-	27	-	ns
t_f	Fall Time	V_{GS}=10V	-	7	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	1700	2720	pF
C_{oss}	Output Capacitance	V_{DS}=15V	-	185	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	160	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.1	2.2	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=2.1A, V_{GS}=0V	-	-	1.2	V
t_{rr}	Reverse Recovery Time[2]	I_S=12A, V_{GS}=0V,	-	21	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	12	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse test

3.Surface mounted on 1 in^2 copper pad of FR4 board, t ≤10sec ; 125 ℃/W when mounted on Min. copper pad.

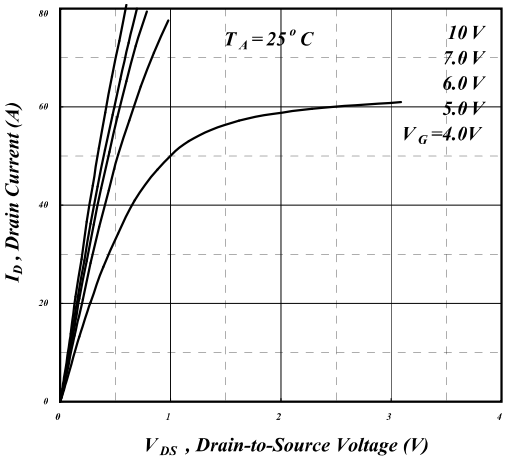


Fig 1. Typical Output Characteristics

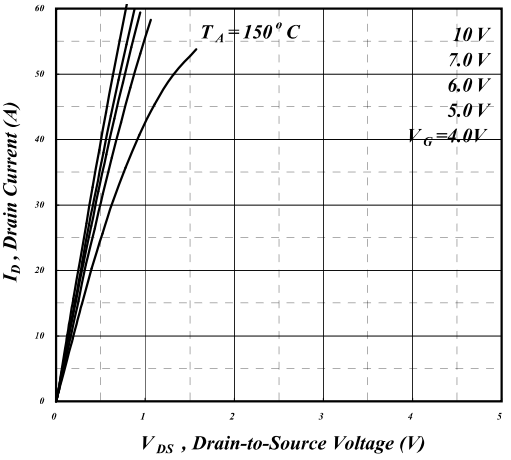


Fig 2. Typical Output Characteristics

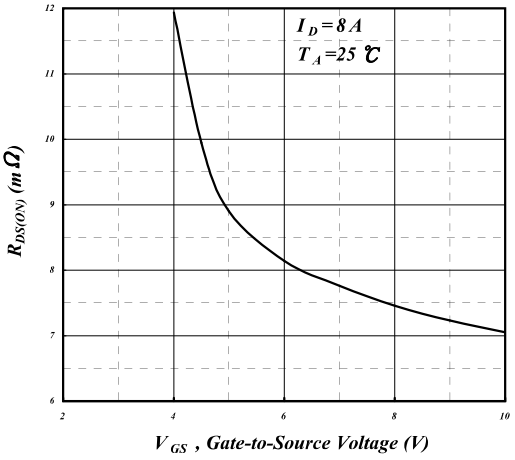


Fig 3. On-Resistance v.s. Gate Voltage

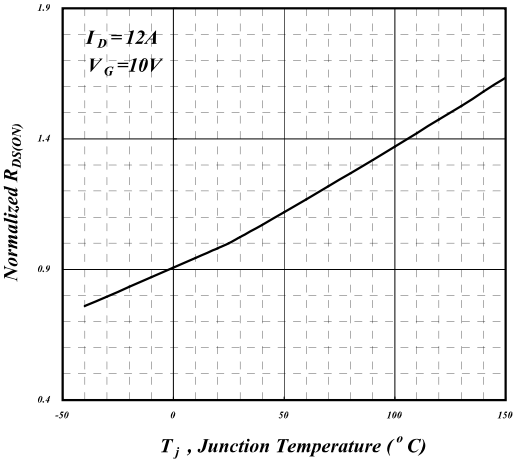


Fig 4. Normalized On-Resistance v.s. Junction Temperature

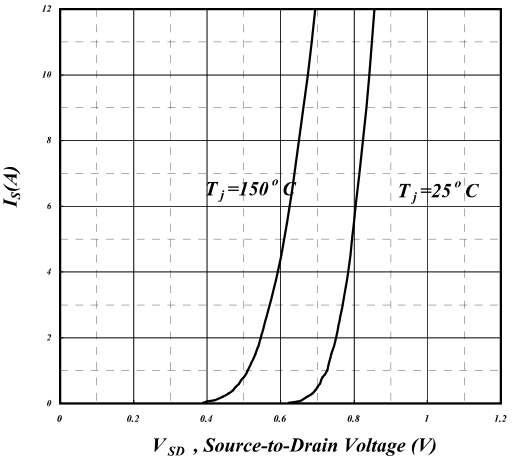


Fig 5. Forward Characteristic of Reverse Diode

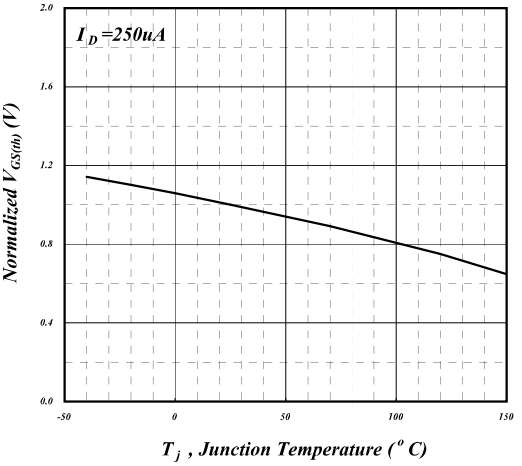


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

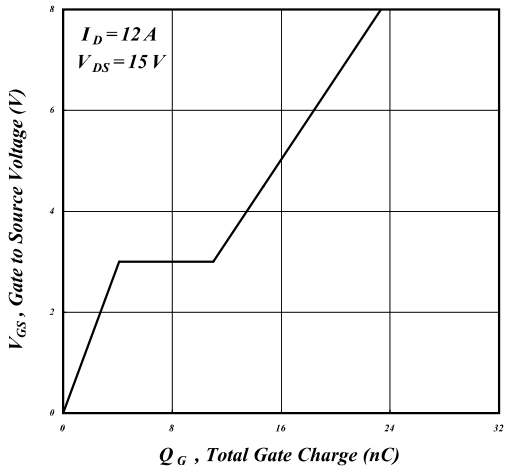


Fig 7. Gate Charge Characteristics

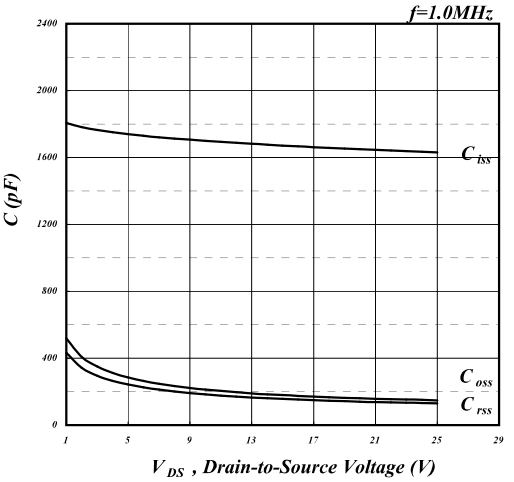


Fig 8. Typical Capacitance Characteristics

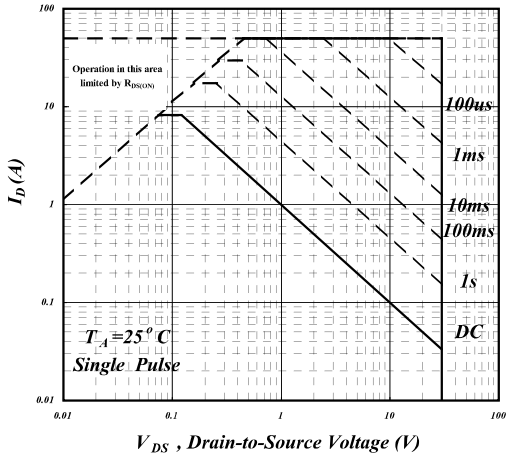


Fig 9. Maximum Safe Operating Area

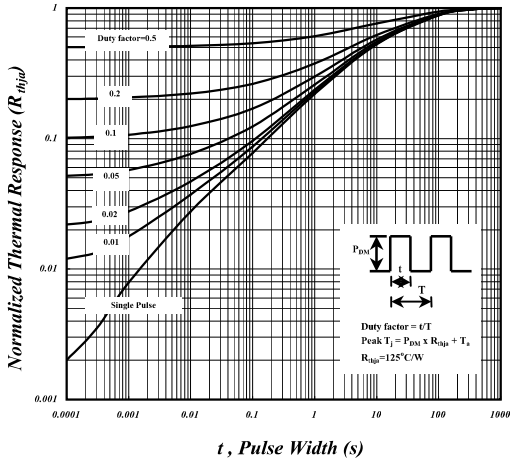


Fig 10. Effective Transient Thermal Impedance

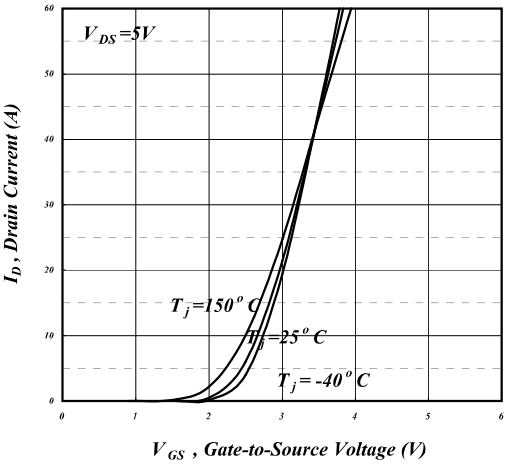


Fig 11. Transfer Characteristics

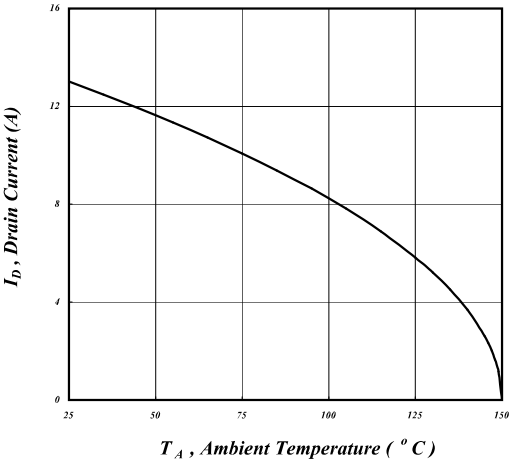
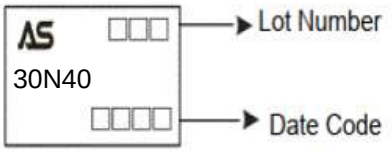


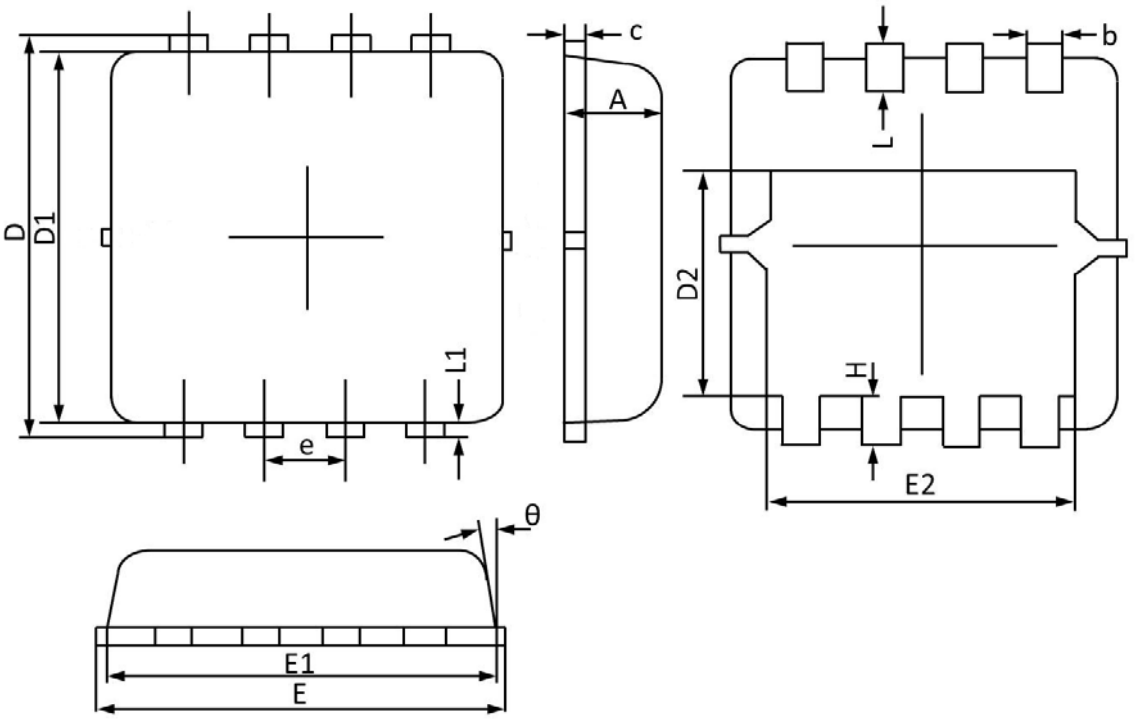
Fig 12. Maximum Continuous Drain Current v.s. Ambient Temperature

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM30N40TD-R	30N40	DFN3*3-8	Tape&Reel	5000

PACKAGE	MARKING
DFN3*3-8	

DFN3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°

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